MOLDING SMD POWER INDUCTOR
MHA2213SG SERIES

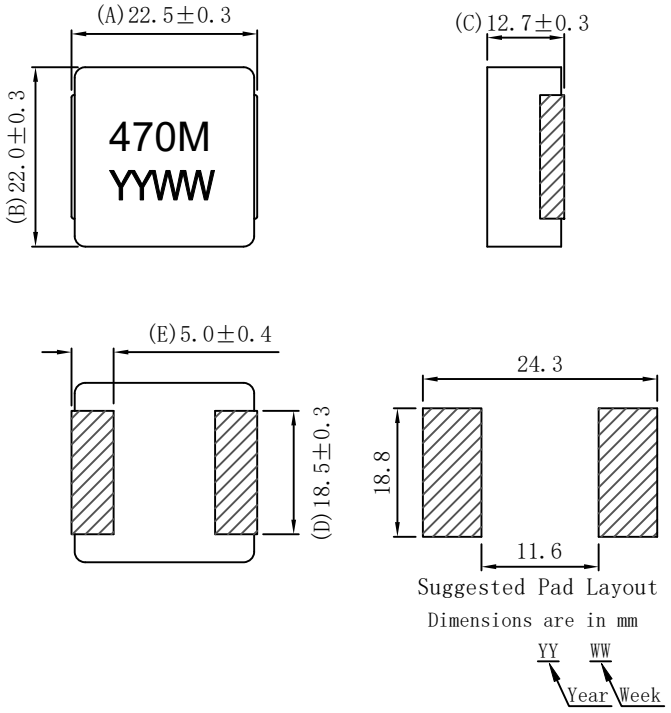
FEATURES

- RoHS compliant,UL94V-0
- Small size (22.80*22.30mm Max),low profile(Height:13.0mm Max)
- Inductance range from 0.47uH to 100.0uH
- Surface mount design
- Magnetic shield construction
- Ultra low buzz noise due to composite construction
- Handle transient current spikes without saturation
- Excellent temperature stability for inductance and saturation
- Tape & reel packing
- Solder profile acc.J-STD-020D

APPLICATIONS

- Low profile ,high current power supplies
- DC/DC converters
- Battery powered devices
- PDA/notebook/desktop/server applications

Part number	Inductance (μH±20%)	DCR(mΩ)@25℃		Irms (A)	Isat (A)
		TYP.	MAX.		
MHA2213SGR47M	0.47	0.56	0.67	80.0	100.0
MHA2213SG1R0M	1.00	0.82	0.89	69.0	71.0
MHA2213SG1R5M	1.50	1.00	1.15	50.0	50.0
MHA2213SG2R2M	2.20	1.20	1.25	48.0	48.0
MHA2213SG3R3M	3.30	1.63	1.77	41.0	41.0
MHA2213SG4R7M	4.70	1.69	1.84	37.0	37.0
MHA2213SG6R8M	6.80	2.84	3.09	36.0	36.0
MHA2213SG100M	10.0	4.04	4.14	28.0	28.0
MHA2213SG150M	15.0	5.62	6.11	23.5	24.0
MHA2213SG220M	22.0	10.60	10.80	17.5	16.0
MHA2213SG330M	33.0	15.10	15.40	15.5	10.5
MHA2213SG470M	47.0	17.30	17.70	13.5	10.0
MHA2213SG680M	68.0	26.20	29.50	12.0	9.5
MHA2213SG750M	75.0	29.76	32.35	11.0	9.0
MHA2213SG820M	82.0	31.46	34.20	10.2	9.0
MHA2213SG101M	100.0	36.25	39.40	9.1	7.0



ABSOLUTE MAXIMUM RATINGS

Operating temperature rang (Including coil' self temperature rise)	-55℃ to +125℃
Storage termperature rang	-55℃ to +125℃

SOLDERING INFORMATION

Peak reflow temperature	250℃
Pin finish	tin

PACKAGING INFORMATION

Tape&Reel	50pcs per reel
Weight	37.5g/pcs

Notes

1. Electrical specification at 25℃.
2. Inductance tested at 100 kHz, 0.25Vrms.
3. Irms is the current that caused a approximate 40℃ temperature rise from 25℃ ambient.
4. Isat is the DC current at which inductance drop approximately 20% from its value without current.
5. The part temperature(ambient + temp.rise) should not exceed 125℃ under worst case operating conditions.Circuit design,component placement, PWB trace size and thickness,airflow and other cooling provisions all affect the part temperature.Part temperature should be verified in the end appliction.